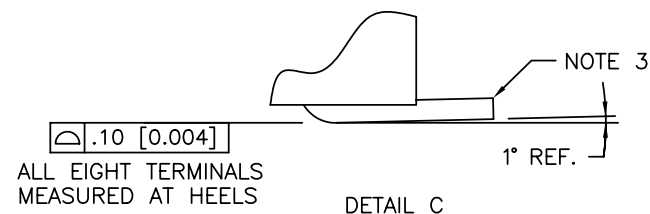
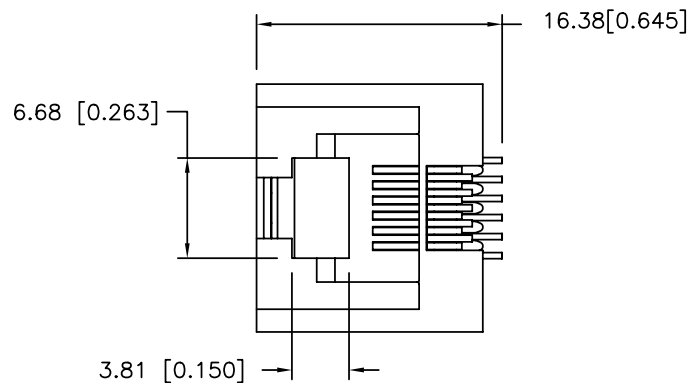


PRODUCT NO.

SEE TABLE



THE MYLAR
ONLY FOR 87545-XXX1C/XXX1CLF

SEE NOTE 7

14.1 [0.555]

15.09 [0.594]

10.84 [0.427]

// .127 [0.005] B

1.29 [0.051]

REF

2.18 [0.086]
TYP

14.1 [0.555]

SEE DETAIL C

1.52 [0.060]

16.53 [0.651]

13.49 [0.531]

6.75 [0.266]

17.50 [0.689]

1.22 [0.048]
REF

5.08 [0.200]

10.16 [0.400] ± 0.05 [0.002]

13.21 [0.520]

7.16 [0.282]

 $\phi 1.90 [0.075] \begin{matrix} +.00 [.000] \\ -.10 [.004] \end{matrix}$
1.27 [0.050] 5X
NON-CUMULATIVE6.35 [0.250]
REF.40 [0.016]
6X

POS #1

VIEW A-A

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		FCI www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X±.3/.XX±.01		projection 	title A-SMT ASSEMBLY VERT 6 POS	
J	V81474	RGD	9/15/96		.XX±.13/.XXX±.005				
K	V12666	LP	1/10/02		.XXX±.051/.XXX±.0020				
L	N05-0035	YS	02/18/05	angles	0° ±2°		MM/INCH 	product family MOD JACK size dwg no A4 87545	
M	N05-0142	ZC	6/2/05	dr	S.DUESTERHOEFT	3/20/96			
N	N07-0217	WG	09/07/07	enrg	Y.BELOPOLSKY	3/20/96			
P	N08-0194	SH	09/08/09	chr	Y.BELOPOLSKY	7/8/96	scale 1:1	sheet 1 of 2	
				appd	Y.BELOPOLSKY	7/8/96			
sheet index		revision		N	N				
		sheet		1	2				



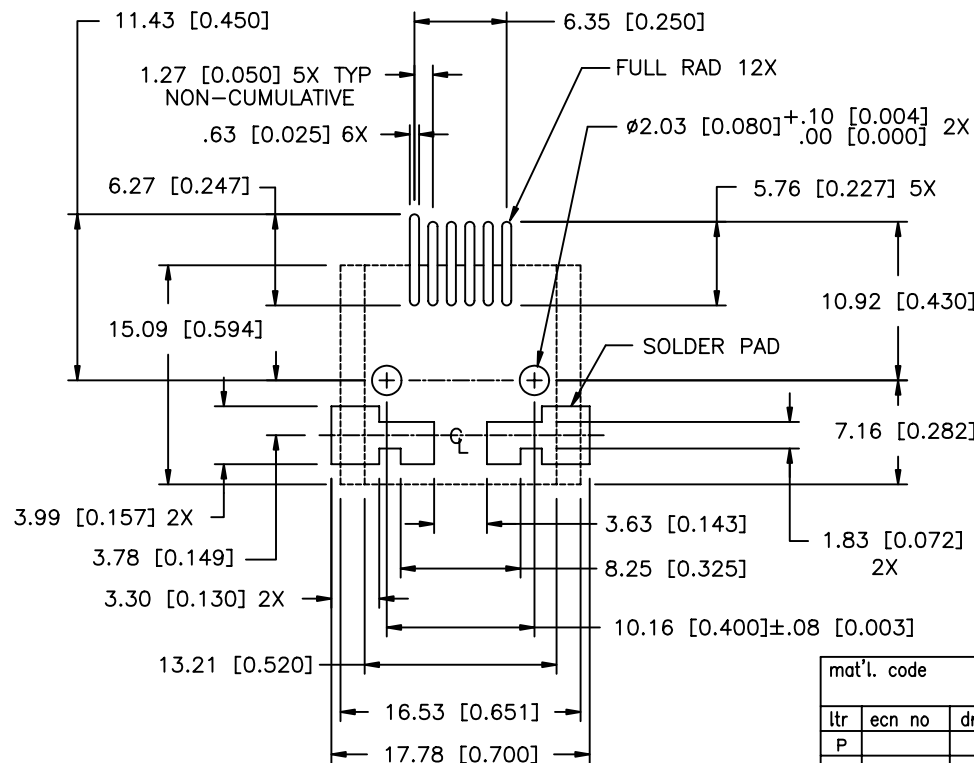
PRODUCT NO.
87545-XXXX 87545-XXXXLF

CONTACT PLATING OPTIONS	
1 = GXT .76μm [30μ"]	NOT TOOLED
2 = GOLD 1.27μm [50μ"]	
3 = PdNi .64μm [25μ"]	
4 = GOLD .76μm [30μ"]	

TERMINAL LOADING OPTIONS
1 = FULLY LOADED 6 POSITION
2 = POS 2,3,4,5 LOADED, 4 POS.

COLOR
1 = BLACK

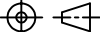
PACKAGE OPTIONS	
BLISTER PACKAGE (TAPE & REEL)	
1 = LOADED FACE UP	
BLISTER PACKAGE (TAPE & REEL)	
2 = LOADED FACE DOWN	
3 = PACKAGED IN TUBES	NOT TOOLED
4 = PACKAGED IN TRAYS	NOT TOOLED



RECOMMENDED PC BOARD L/O

NOTES:

- MATERIAL: HOUSING - THERMOPLASTIC V-0
CONTACT - PHOSPHOR BRONZE
- PLATING: SOLDER TAILS - FOR 87545-XXXX : 2.54 μm [100 μIN] MIN. TIN LEAD OVER 2.54 μm [100 μIN] NICKEL
FOR 87545-XXXXLF: 2 μm [80 μIN] MIN. PURE MATTE TIN OVER 1.27 μm [50 μIN] MIN. NICKEL
HOLDDOWN - FOR 87545-XXXX: 2.54 μm [100 μIN] MIN TIN LEAD OVER 2.54 μm [100 μIN] NICKEL
FOR 87545-XXXXLF: 2μm [80 μIN] MIN. PURE TIN OVER 1.27 μm [50 μIN] MIN. NICKEL
CONTACT AREA PLATING - SEE CHART ON SHEET 2
- MAX "TOE UP" AT TIP = 0.127 [0.005]
- IF LF P/N PACKAGING MEETS GS-14-920 SPECIFICATION.
- THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 40 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- IF LF P/N THE PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
- APPLY THE MYLAR ON THE P/N 87545-XXX1 WITH SUFFIX "C" FOR PICKING UP. FOR INSTANCE 87545-4111CLF .

mat'l. code				tolerances unless otherwise specified			CUSTOMER COPY		 www.fciconnect.com	
ltr	ecn no	dr	date	linear	.X±.3/.XX±.01			projection 	title A-SMT ASSEMBLY VERT 6 POS	
P					.XX±.13/.XXX±.005					
					XXX±.051/.XXX±.0020					
				angles	0° ±2°				product family MOD JACK size dwg no	
				dr	S.DUESTERHOEFT	3/20/96	scale 1:1			
				engr	Y.BELOPOLSKY	3/20/96				
				chr	Y.BELOPOLSKY	7/8/96		A4	87545	
				appd	Y.BELOPOLSKY	7/8/96	sheet 2 of			
sheet index	revision sheet									